

Click here for the 3D model.

| Dimensions |  |
| :--- | :--- |
| Chip Size | 0402 |
| L | $1 \mathrm{~mm}+/-0.05 \mathrm{~mm}$ |
| W | $0.5 \mathrm{~mm}+/-0.05 \mathrm{~mm}$ |
| T | $0.5 \mathrm{~mm}+/-0.05 \mathrm{~mm}$ |
| S | 0.3 mm MIN |
| B | $0.3 \mathrm{~mm}+/-0.1 \mathrm{~mm}$ |


| Packaging Specifications |  |
| :--- | :--- |
| Packaging | T\&R, 180mm, Paper Tape |
| Packaging Quantity | 10000 |


| General Information |  |
| :--- | :--- |
| Series | ESD SMD Auto COG |
| Style | SMD Chip |, | SMD, MLCC, Temperature Stable, Electro |
| :--- | :--- |
| Static Discharge, Automotive Grade |


| Specifications |  |
| :--- | :--- |
| Capacitance | 2200 pF |
| Measurement Condition | 1 kHz 1.0 Vrms |
| Capacitance Tolerance | $1 \%$ |
| Voltage DC | 25 VDC |
| ESD Level per AEC-Q200 | $6,000 \mathrm{~V} \mathrm{ESD}$ Level |
| Dielectric Withstanding Voltage | 62.5 VDC |
| Temperature Range | $-55 /+125^{\circ} \mathrm{C}$ |
| Temperature Coefficient | COG |
| Capacitance Change with Reference to $+25^{\circ} \mathrm{C}$ | $30 \mathrm{ppm} / \mathrm{C}, 1 \mathrm{kHz}$ |
| and O VDC Applied (TCC) | 1.0 Vrms |
| Dissipation Factor | $0.1 \% 1 \mathrm{kHz} 1.0 \mathrm{Vrms}$ |
| Aging Rate | $0 \% \mathrm{Loss} / \mathrm{Decade}$ |
| Insulation Resistance | Hour |

